

The background of the slide is a detailed, high-angle photograph of a NVIDIA Tesla V100 GPU. The GPU is a large, square, black integrated circuit mounted on a dark printed circuit board (PCB). The surface of the GPU is covered in a complex grid of gold-colored pads and traces. Various components, including capacitors and other smaller chips, are visible on the PCB around the GPU. The lighting is dramatic, highlighting the metallic surfaces and the intricate patterns of the chip.

Trusted Microelectronics Joint Working Group

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Dr. Daniel Radack, IDA

Ms. Catherine Ortiz, Defined Business Solutions

Mr. David Chesebrough, NDIA

October 26, 2017

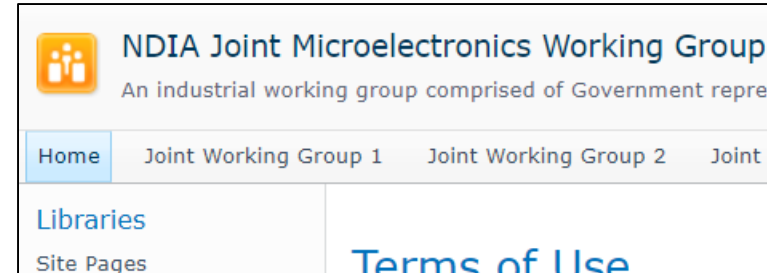
- **First Workshop Held on June 28, 2013**
- **Ten Workshops have since been held**
 - Hundreds have participated from government, industry and academia
 - A great deal of focus on **Trust** but also on **Access, Industrial Base, National Competitiveness, Cost** and **Collaboration/Cooperation**
 - Participant interest in ongoing activity led to:
 - A call for a working group to be formed during the February 2016 workshop the group was subsequently formed from volunteers (many more than expected)

- Obtaining Trusted and assured microelectronics is critical to maintaining the U.S. military's technological advantage

- As consolidation and the migration offshore of integrated circuit design and manufacturing capabilities continue, the defense industry faces increasing challenges to obtain those critical components from Trusted Suppliers

- An NDIA Trusted Microelectronics Joint Working Group (TM JWG) was formed to collaboratively develop mitigation strategies for the decreasing access to assured microelectronics for defense and national security systems

- Over the 14-month study period, the NDIA TM JWG membership reached 80 participants from nine government offices, 28 separate defense companies, and nine non-profit and FFRDC organizations



TM JWG Members Collaborated on private Sharepoint Site

- The TM JWG formed four teams to address critical challenges impacting defense microelectronics supply
 - Future Needs & System Impact of Microelectronics Technologies: Team Leader: Charley Adams, Northrop Grumman
 - Trustable Access to Leading Edge Technology: Team Leader: Ezra Hall, GLOBALFOUNDRIES
 - Trustable Microelectronics Standard Products: Team Leader: Ken Lebo, Jacobs Engineering Group
 - New Methods to Instill Trust in Commercial Semiconductor Fabrication: Team Leader: Pat Hays, Boeing

TM JWG Members

As of February 15th, 2017



Charles Adams
Northrop Grumman

Dean Brenner
Honeywell International Inc.

Gerry Etzold
Etzold Technology Consulting

Adam Hauch
DSS

Scott Jordan
Jazz Semiconductor
Trusted Foundry, Inc.

Grant Meyer
SRI International

Paul Quintana
Microsemi

Nicolas Sramek
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Contract Support to ODASD(SE)

Saverio Fazzari
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Pat Hays
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Brett Attaway
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of Organizations / # of Participants

Industry: 28/40

FFRDCs: 3/10

Academia/Non-Profits: 6/8

Government: 9/22

Total: 46/80

TM JWG Members

As of February 15th, 2017



Government

DASD (SE)

Defense Microelectronics Activity

DSS

Department of Commerce

Department of Defense (NSA)

Naval Research Laboratory

NSWC Crane

OSD Manufacturing & Industrial Base Policy

USAF SMC

Industry

Aeroflex (Cobham)	DRAPER	Intrinsic Corp	Novati Technologies
Avnet	Etzold Technology Consulting	Jacobs	Rockwell Collins
Boeing	GLC Consulting, LLC	Jazz Semiconductor Trusted Foundry, Inc.	SMI Inc.
Booz Allen Hamilton	GLOBALFOUNDRIES	Lockheed Martin Corporation	Techtonic Labs
Cadence	Honeywell International Inc.	MacAulay-Brown, Inc.	TechVision21
Cypress Semiconductor	IBM/IBM GBS	Microsemi	Vantagepoint Advisors
Defined Business Solutions	Intel Federal	Northrop Grumman	Xilinx

FFRDCs

The Aerospace Corporation

Institute for Defense Analyses

Sandia National Laboratories

Academia/Non-Profits

Alfred University

Ohio State University

AIM Photonics Institute

SRI International

MIT Lincoln Laboratory

University of Central Florida

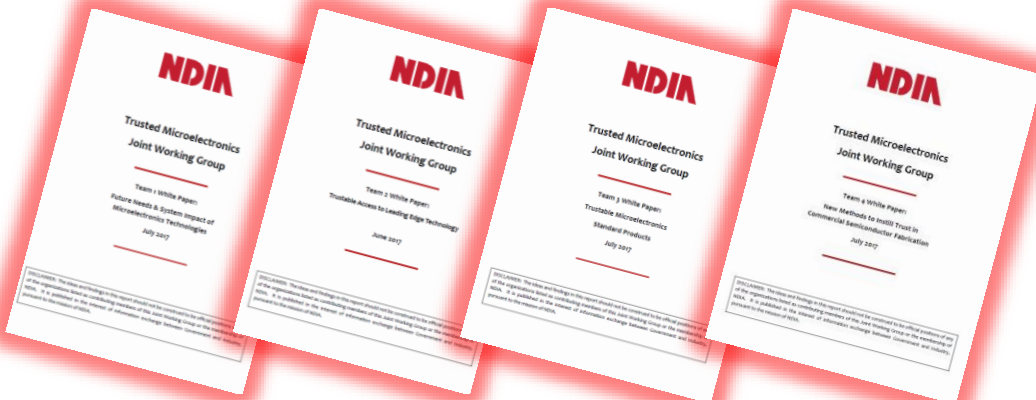
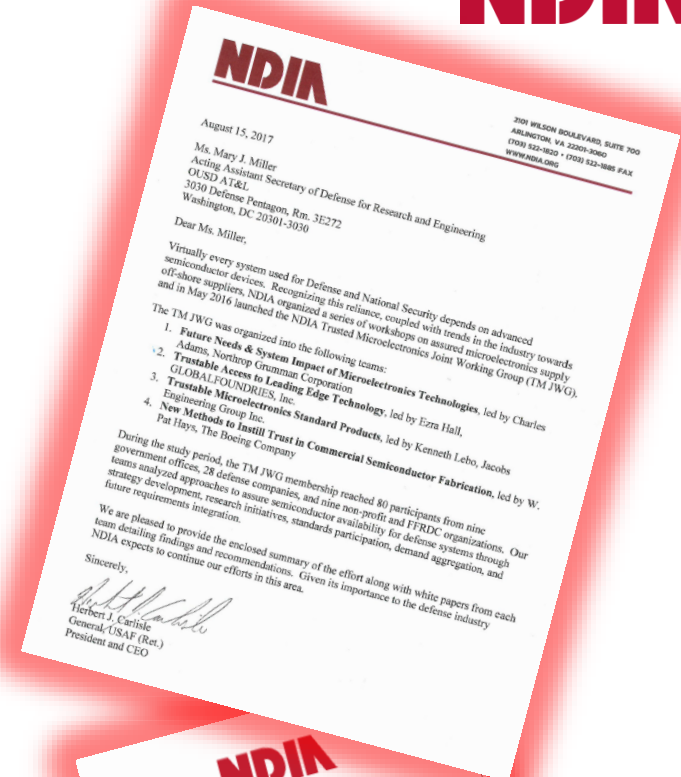
Potomac Institute for Policy Studies

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The Results from the TM WG



- TMW WG Findings Transmitted to ASD(R&E) on August 29, 2017
- Findings Publicly Posted on the NDIA site
- Includes Reports from All 4 Teams



<http://www.ndia.org/divisions/working-groups/tmejwg/final-team-reports>

Key Recommendations

Create a U.S. National Semiconductor Strategy

Adapt DoD Acquisition Practices to Align with Commercial Market

Increase DoD Market Influence

Adopt New Trust and Assurance Models

Launch R&D to Achieve Trust and Security in Un-trusted Fabs

Create a U.S. National Semiconductor Strategy

- Viewed by the TM JWG as single most impactful action to assure access to technologies
- Recommends a Government-Industry-Academia consortia or coalition to develop plan, including and beyond DoD's requirements
- Would prioritize essential technologies for loss contingency protections and create a technology roadmap to identify investments

Adapt DoD Acquisition Practices to Align with Commercial Market

- Recommends defense programs be provided new methods to purchase technology on commercial terms after trustworthiness evaluation
- Develop approaches to adopt commercial solutions and intellectual property with well-defined risk mitigations
- Develop a process to plan sustainment needs during initial product purchases

Increase DoD Market Influence

- Increase market influence by exchanging research investment for access to commercial products
- Aggregate demand across DoD programs, other USG offices, and non-USG industries that have similar component and system integrity concerns.

Adopt New Trust and Assurance Models

- Develop program-specific Trust Plans and Technical Implementation Guides to identify security measures for each step in the product flow from design through test
 - The Guides would factor technology-enabled mitigations and countermeasures into security requirements
 - The Plans could expand today's Trust offerings by defining the boundaries for assurance spectrums or "tiers of trust" levels, and would cover component categories beyond ASICs.

Launch R&D to Achieve Trust and Security in Un-trusted Fabs

- Launch near-term research and development to address the security concerns of existing commercial technology capabilities
 - Separate from, but coordinated with, the national semiconductor strategic plan
- Establish a government focus to track future technology trends and impacts is recommended to continuously identify technology renewal opportunities and capabilities gaps.

Outcome and Impact



- **The NDIA Trusted Microelectronics Joint Working Group demonstrated the value of government-industry collaboration when addressing critical issues facing the Department of Defense and the Defense Industrial Base**
 - There was immense participation throughout government, industry and academia
- **This work coincided with accelerated concern over the issues**
 - DoD establishment of the JFAC and T&AM program
 - Studies – PCAST, DSB Cyber Supply Chain Task Force . . .
 - Presidential EO on Industrial Base (Includes semiconductors)
- **Given the importance of this work to National Security Community NDIA plans to leverage the Joint Working Group into a standing NDIA Division so that it may continue under an officially recognized charter**
 - This division is tentatively being called the NDIA Electronics Division
- **Further information on the Workshops and TM JWG reports can be found at www.ndia.org/divisions/working-groups/tmejwg**

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